

## LYNRED BY SOFRADIR & ULIS

## INFRARED IMAGING SOLUTIONS AND CHALLENGES

Patrick Abraham EPIC World Photonics Technology Summit Berlin 30/08/2019







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LYNRED - 1. WEARE

#### About LYNRED KEY FIGURES AND SHAREHOLDERS



 RESEARCH PARTNER<br/>CEA LETI- ONERA- III-V LAB
 80%<br/>EXPORT

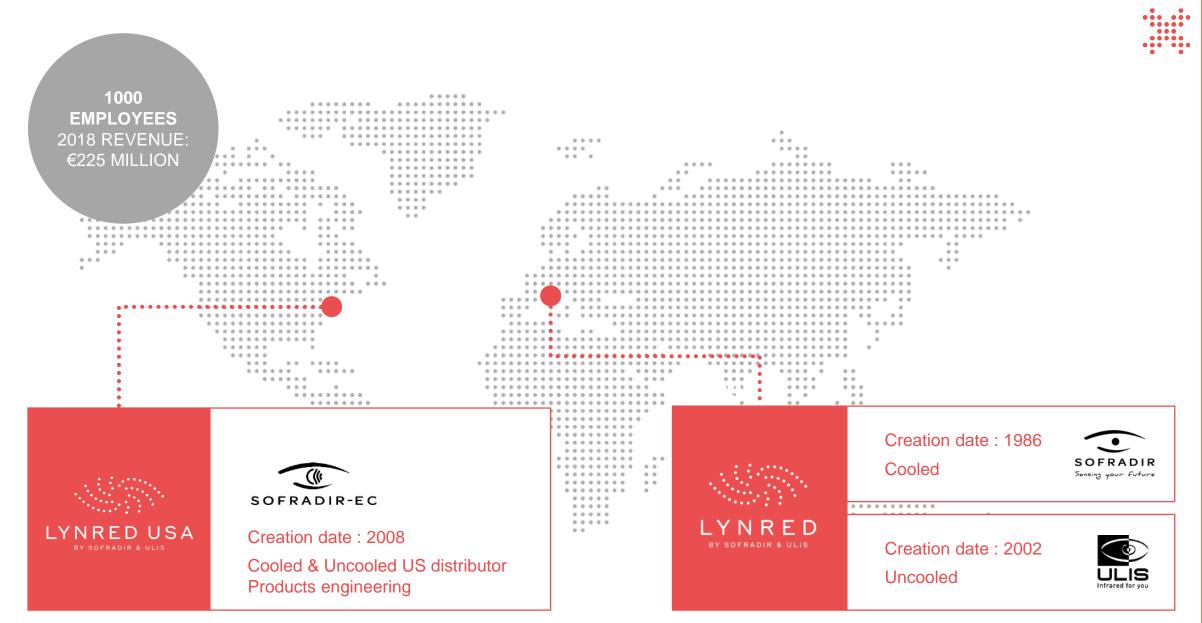
 Image: Stress of the stress

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GLOBAL INDUSTRY LEADER IN INFRARED DETECTORS offering the largest product portfolio



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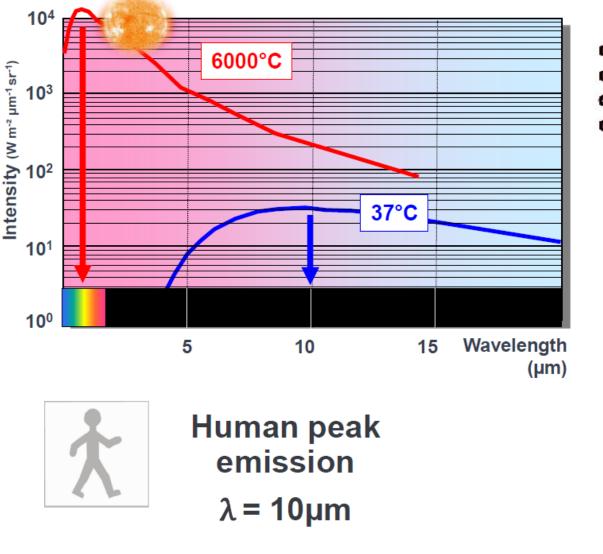




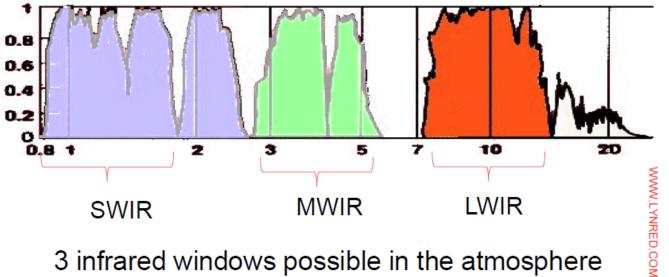
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#### **BACK TO BASICS, INFRARED DETECTION Planck** Atmosphère

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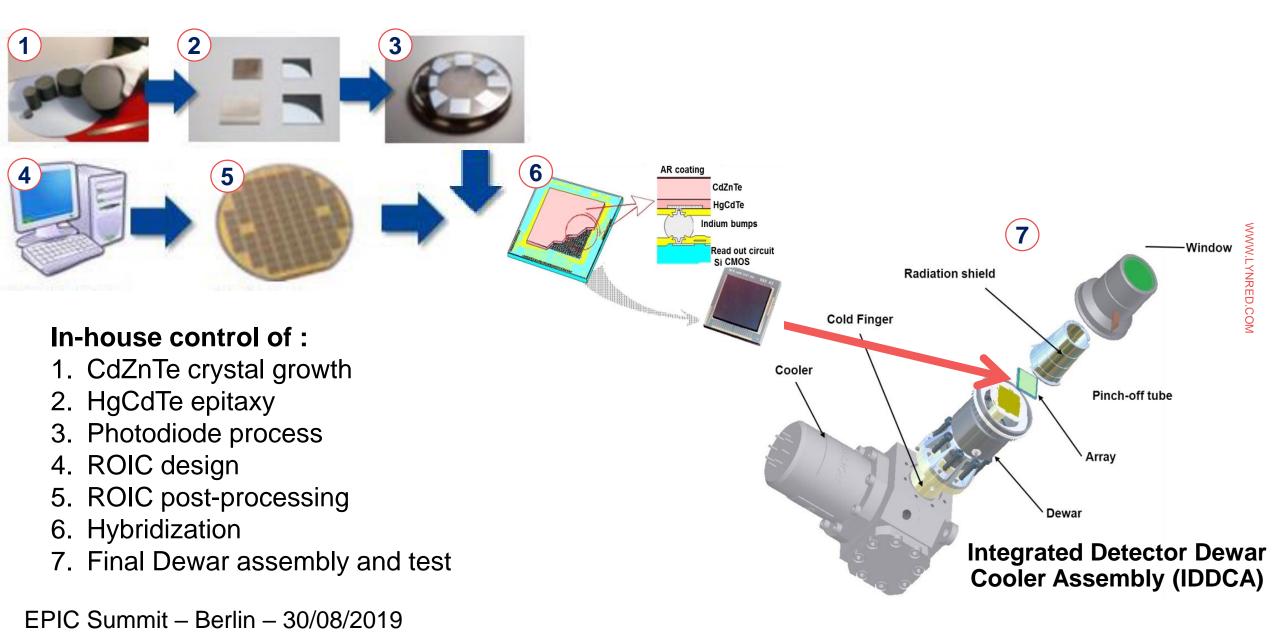


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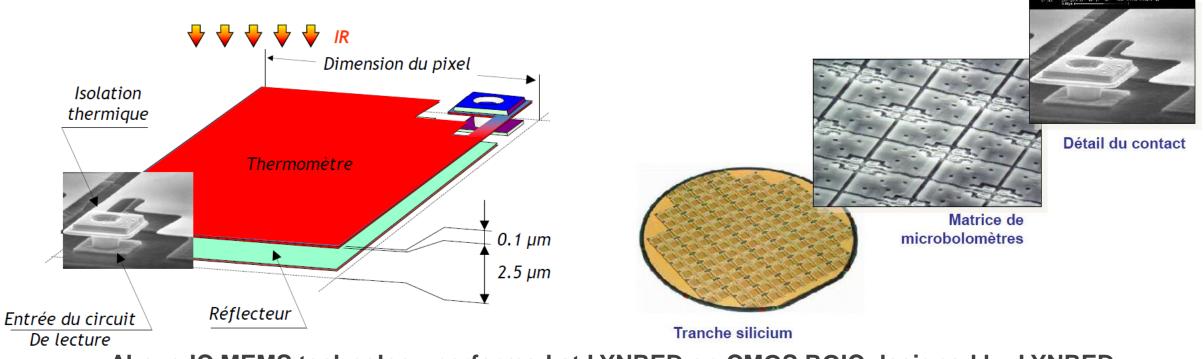


🖊 븆 븆 븆 IR ABSORBING MATERIAL 븆 븆 븆 🆊 IR THERMOMETER PHOTODETECTOR THERMAL INSULATION **READ OUT CIRCUIT READ OUT CIRCUIT** SIGNAL SIGNAL Photovoltaic detector Thermal detector MCT and InGaAs

# Cooled Infrared detector based on hybridized sensors



# IR detectors based on microbolometers



Above IC MEMS technology performed at LYNRED on CMOS ROIC designed by LYNRED

#### MEMS technology followed by

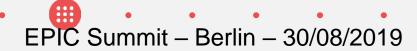
- Dicing
- Packaging (integration, pumping)
- Test



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About LYNRED Business Model





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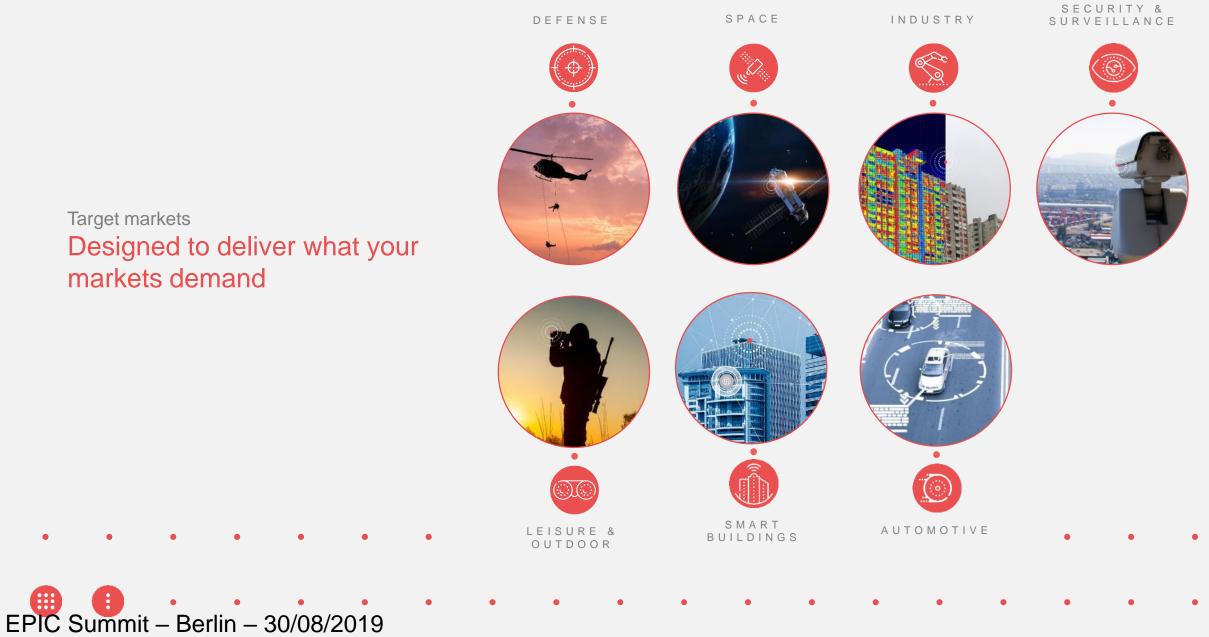
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•	•	•	•	•	LYNRED target markets
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LYNRED - 3. WE SERVE



Target markets Designed to deliver what your markets demand

# Thermal Imaging Applications

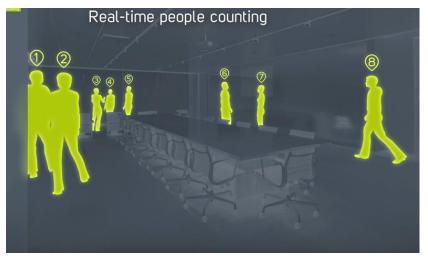
#### Security



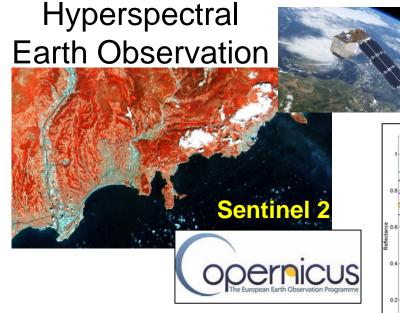
#### Automotive



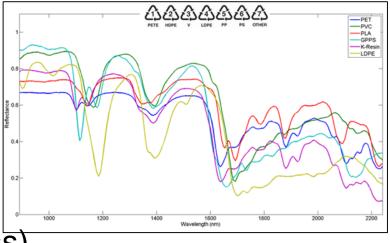
#### Smart building



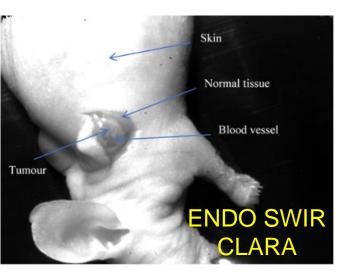
# Multi/Hyper Spectral Imaging Applications



### Machine Vision



### **Medical Diagnostic**



## Smart Farming (hydric stress)



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### **Gas Detection**





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Overview of the future trends

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# NEXT CHALLENGES

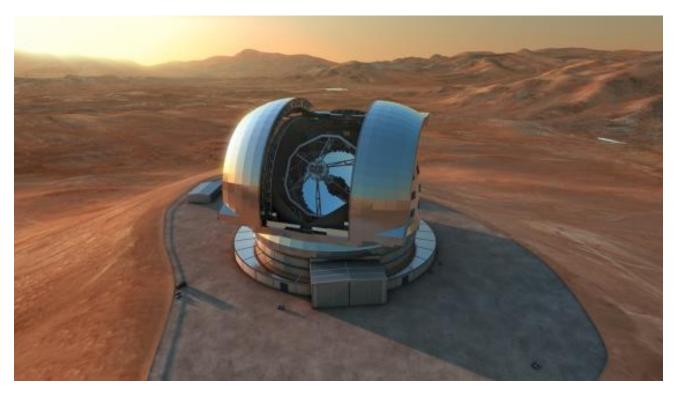
## □ No matter the technology, products need to be :

- More compact (SWAP)
- Less expensive
- Higher performance
  - More pixels and resolution
  - Higher sensitivity
  - Less cross talk between pixels (better MTF)
  - Less noise
  - Faster frame rate
  - Multispectral or Hyperspectral capability
  - Integrated image pre-treatment
    - Very large high performance detectors for Astronomy and Space applications
    - High operating temperature MWIR sensors for SWAP applications
    - Low cost small pitch modules for Automotive and Smart building applications

# High performance large focal plane arrays (2k<sup>2</sup> : 2048 x 2048)

## >Space observation

>Astronomy



FPA dimension > 30 x 30 mm<sup>2</sup>
→ Larger substrates & epitaxy

Dark current < 1 e- / sec</li>
→ Very low defect material and process

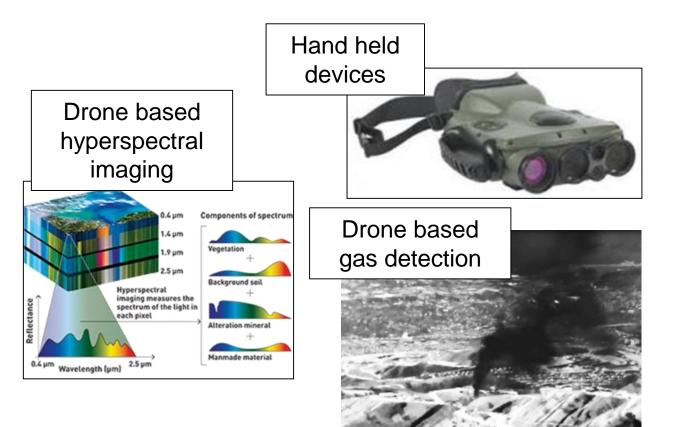
Read Out Noise ~ 10 eROIC cross talk < 3 %</li>
→ High performance CMOS design

Quantum efficiency > 75 % → Device design optimisation



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# High operating temperature MWIR sensors for SWAP applications



High operating temperature ~ ≥140 K

Very low dark current

- New detection configuration (long minority carrier life time)
- ➔ Very low defect material and process

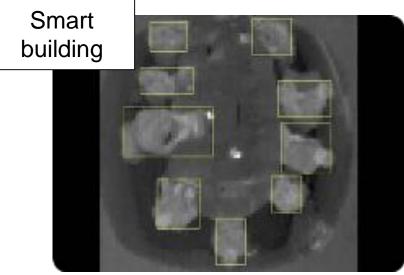
#### Compact cryostat

- → New materials and designs
- New and more compact cooler adapted to the new operating temperature



Next generation microbolometer sensors





Low cost systems → Small pitch

→ New volume packaging solutions

Faster frame rate→ Design optimization

Compact →New volume packaging solutions



# Wrap-up

#### **Product development:**

- Many technology fields involved
- Being expert in every single field is complicated
- → We are paying attention to potential new solutions

#### **Application development:**

- Many potential applications for IR sensing
- Identifying all of them is complicated

→ We are paying attention to your needs in IR sensing and imaging

### **THANK YOU** FOR YOUR ATTENTION

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## This presentation was presented at EPIC World Photonics Technology Summit 2019

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